



Material Content Data Sheet



Sales Product Name				IPB70P04P4-09		Issued		25. September 2017	
MA#				MA000756684					
Package				PG-TO263-3-2		Weight*		1557.68 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.074	0.13	0.13	1332	1332	
leadframe	non noble metal	iron	7439-89-6	0.304	0.02		195		
	inorganic material	phosphorus	7723-14-0	0.091	0.01		59		
	non noble metal	copper	7440-50-8	304.026	19.52	19.55	195179	195433	
wire	non noble metal	aluminium	7429-90-5	5.359	0.34	0.34	3440	3440	
encapsulation	organic material	carbon black	1333-86-4	10.283	0.66		6602		
	plastics	epoxy resin	-	113.115	7.26		72618		
	inorganic material	silicondioxide	60676-86-0	562.147	36.10	44.02	360886	440107	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6199	6199	
plating	non noble metal	nickel	7440-02-0	0.228	0.01		147		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	147	
solder	noble metal	silver	7440-22-4	0.050	0.00		32		
	non noble metal	tin	7440-31-5	0.040	0.00		26		
	non noble metal	lead	7439-92-1	1.923	0.12	0.12	1235	1293	
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		106		
	non noble metal	iron	7439-89-6	0.548	0.04		352		
	non noble metal	copper	7440-50-8	547.666	35.16	35.21	351591	352049	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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